

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

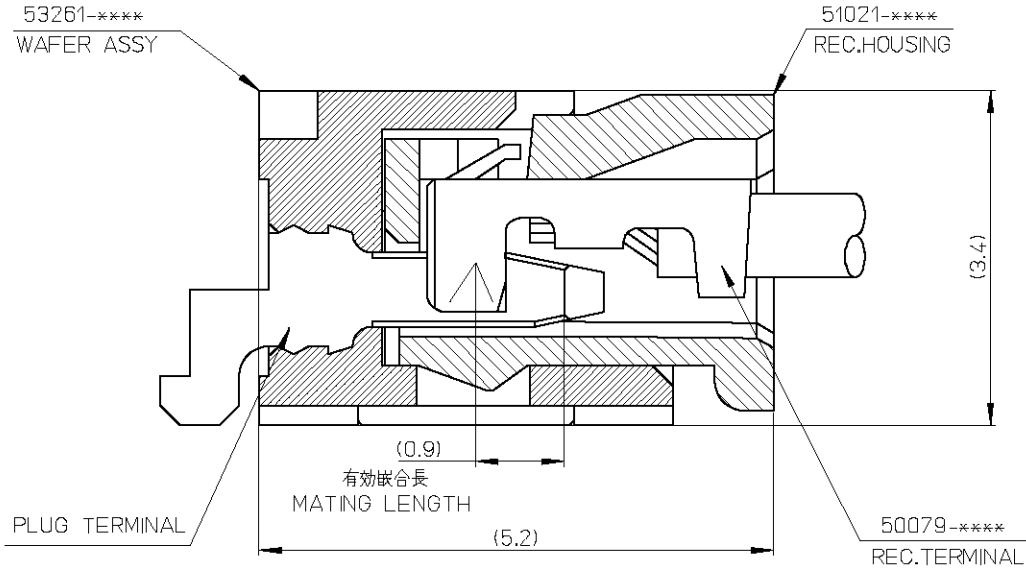
C

B

B

A

A



53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: AOYAGI 2006/02/02 CHKD: MAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>		SCALE ---	DESIGN UNITS <b>METRIC</b>	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY Y. AOYAGI	DATE 2006/01/30	TITLE <b>1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION</b>		
	10 <sup>OVER</sup> 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED		
	30 <sup>OVER</sup>	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	DOCUMENT NO. <b>SD-51021-002</b>		
	ANGULAR	± --- °	MATERIAL NO. <b>SEE CHART</b>		SHEET NO. 1 OF 1		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9

8

7

6

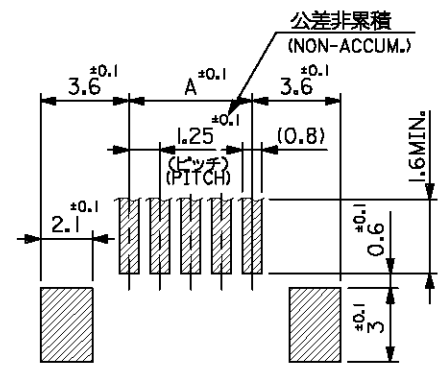
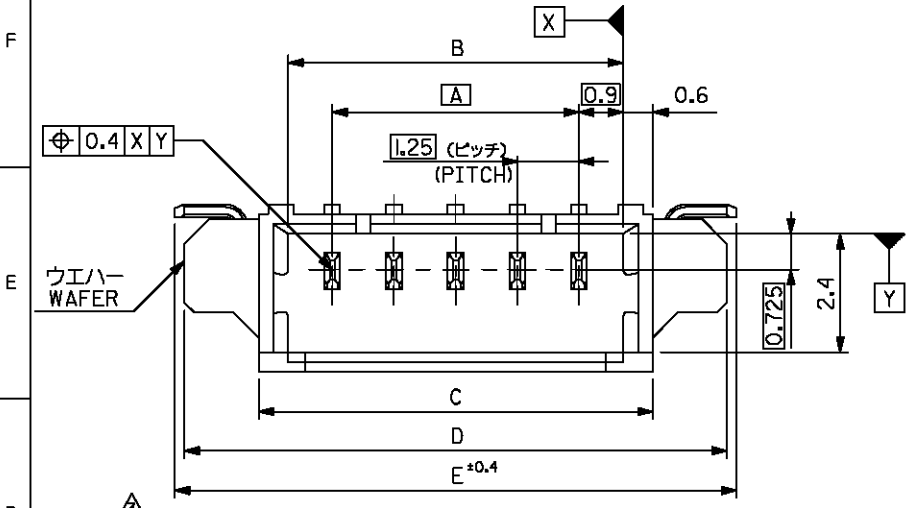
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4

3

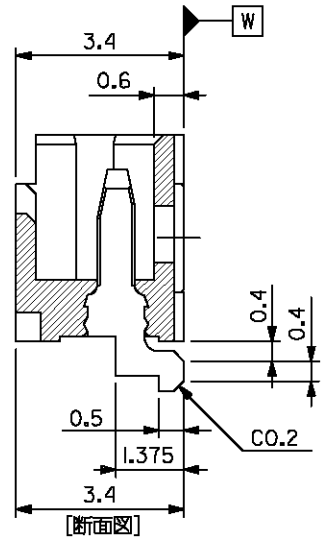
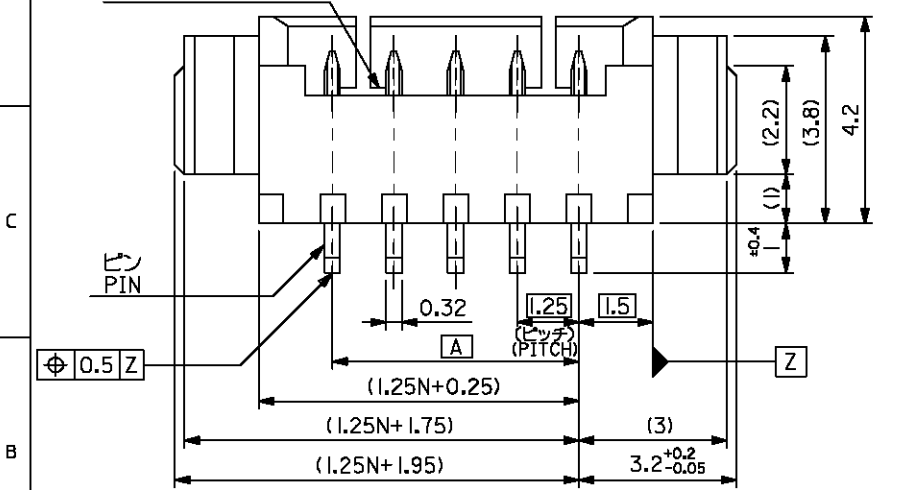
2

10 9 8 7 6 5 4 3 2 1



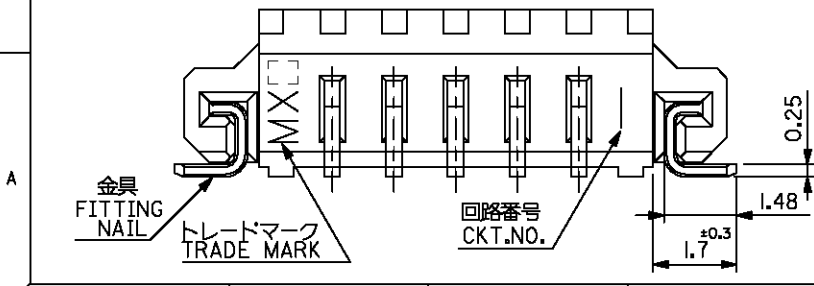
参考基板レイアウト  
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)  
(SCALE 5:1)

- 注記 NOTES**
1. 嵌合相手: 51021 シリーズ  
MATES WITH: 51021 SERIES
  2. 材質 MATERIAL  
ウエハー: NYLON46, UL94V-0  
ピン: リン青銅, 半田メッキ  
PIN: PHOS-BRO., Sn-Pb(9:1) 3 μmMIN. OVER Cu 1 μmMIN. PLATING  
金具: リン青銅, 半田メッキ  
FITTING NAIL: PHOS-BRO., Sn-Pb(9:1) 2 μmMIN. OVER Cu 1 μmMIN. PLATING
  3. ロック窓は2、3種は1箇所、4種以上は2箇所とする。  
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
  4. ソルダテール部のスレ量及び金具(補強板)のスレ量は基準面 W に対し、上方向 0.05 MAX.、下方向に 0.1 MAX. とする。  
OFFSET BETWEEN BASIS PLANE W TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:  
UPPER SIDE: 0.05MAX.  
LOWER SIDE: 0.1MAX.



断面図

23.9	23.5	20.5	19.3	17.5	53261-1510	15
22.65	22.25	19.25	18.05	16.25	-1410	14
21.4	21	18	16.8	15	-1310	13
20.15	19.75	16.75	15.55	13.75	-1210	12
18.9	18.5	15.5	14.3	12.5	-1110	11
17.65	17.25	14.25	13.05	11.25	-1010	10
16.4	16	13	11.8	10	-0910	9
15.15	14.75	11.75	10.55	8.75	-0810	8
13.9	13.5	10.5	9.3	7.5	-0710	7
12.65	12.25	9.25	8.05	6.25	-0610	6
11.4	11	8	6.8	5	-0510	5
10.15	9.75	6.75	5.55	3.75	-0410	4
8.9	8.5	5.5	4.3	2.5	-0310	3
7.65	7.25	4.25	3.05	1.25	53261-0210	2
E	D	C	B	A	ENG. NO.	種数 CKT.



REVISED EC NO.: J2005-1631 DRAWN: SUZUKI CHKD: KTOYODA APPR: NUKITA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	DESCRIPTION	10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY HSEKINE 89/10/18	DATE 94/06/23	TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT RIGHT ANGLE
G	REV	ANGULAR ±3°	APPROVED BY MFUKUSHI 94/06/23	DATE 94/06/23	MATERIAL NO.	MOLEX INCORPORATED
			SEE DRAWING	DOCUMENT NO. SD-53261-**10	SHEET NO. 1 OF 1	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

E

D

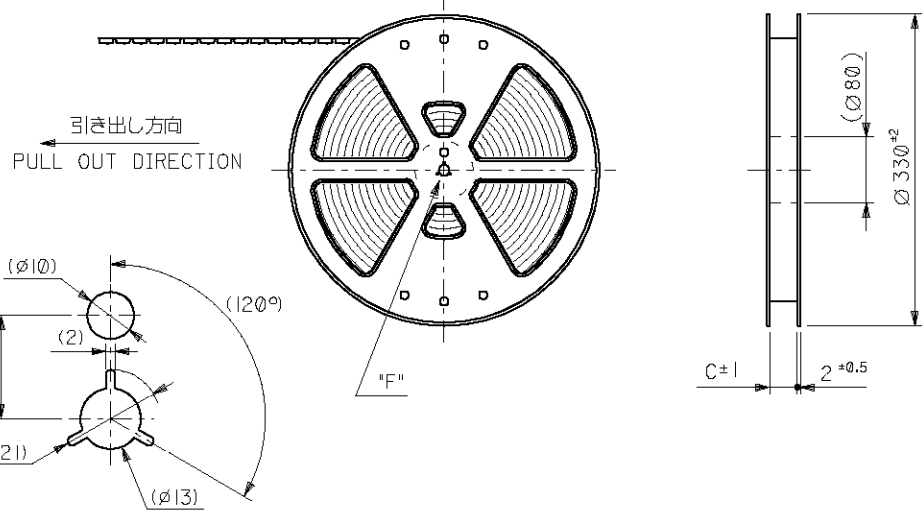
C

B

A

MM

DIMENSIONS IN METRIC DO NOT SCALE DRAWING



注記 NOTES

- 53261-\*\*\*10 の詳細寸法については図面 SD-53261-\*\*\*10 を参照下さい。  
RE DETAILED DIMENSIONS, SEE SD-53261-\*\*\*10.
- 梱包数量: 1000個/リール  
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH  
トップテープリーダー部 TOP TAPE LEADER PART 175 ± 0.25  
トップテープ未接着部 TOP TAPE NON-BONDED PART 25 ± 0.5



- トップテープの剥離強度: 0.1N ~ 0.59N (10.2 ~ 60gf) (剥離方向は下図参照)  
PEELING OFF FORCE OF TOP TAPE: 0.1N ~ 0.59N (10.2 ~ 60gf)  
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)

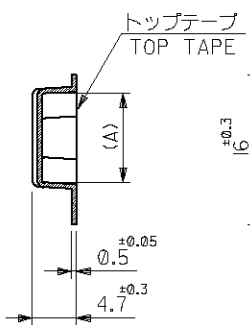
<剥離速度: 300mm/min (参考)>  
PEELING SPEED: 300mm/min. (REFERENCE)



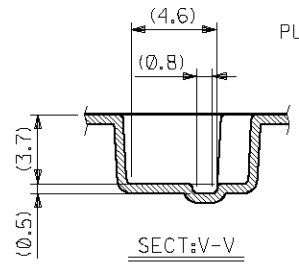
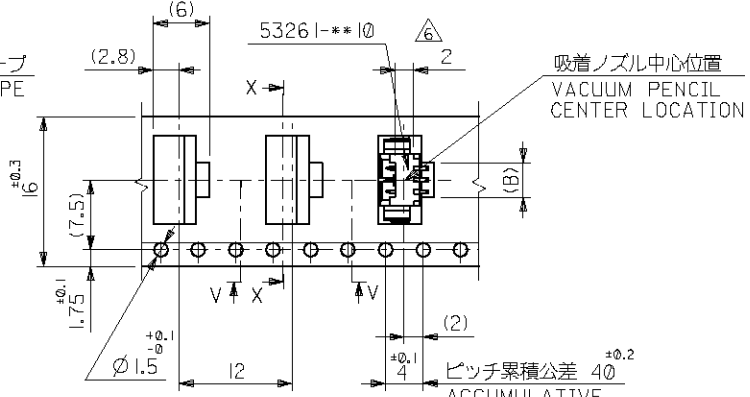
- 材料 (MATERIAL)  
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)  
トップテープ (TOP TAPE): PET, PE, PEF  
リール (REEL): ポリスチレン (P.S) <リサイクル材含む>  
POLYSTYRENE (P.S) <RECYCLE MATERIAL CONTAINED>

△ コネクタ、ハウジング平面部  
CONNECTOR, HOUSING FLAT AREA

DETAIL "F"



SECT: X-X



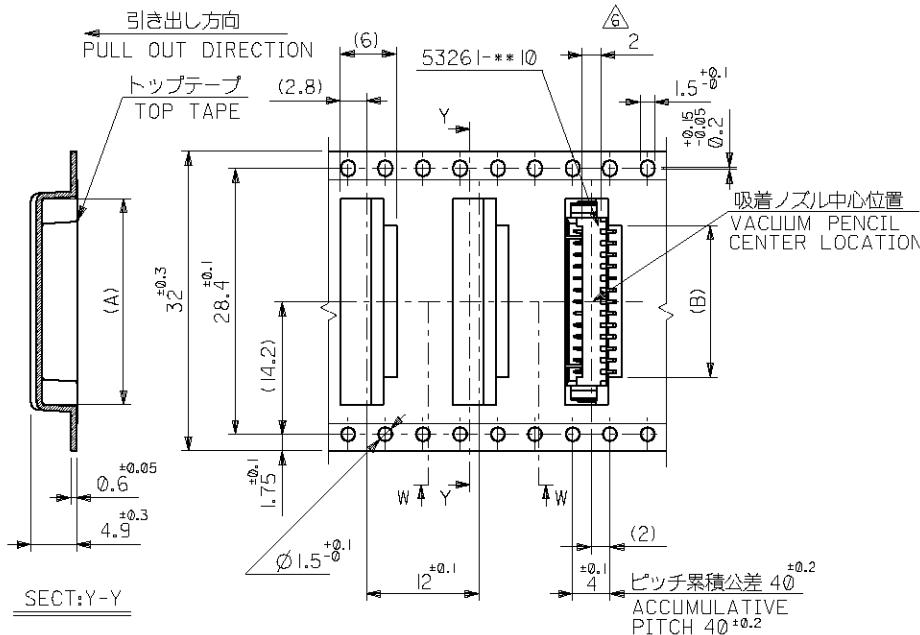
SECT: V-V

16mm幅キャリアテープ  
16mm WIDTH CARRIER TAPE

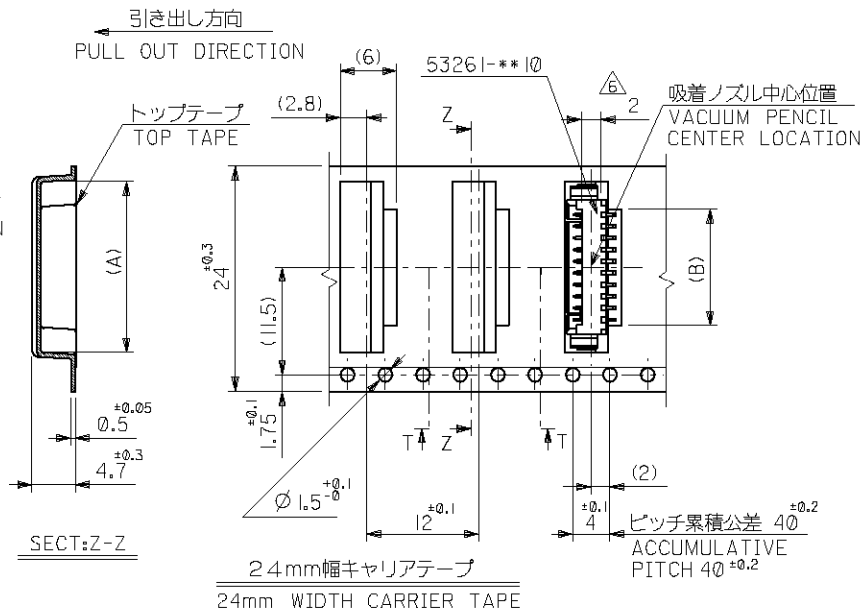
角度 ANGLE	±30
30以上 OVER	+0.3
10以上 30未満 OVER	+0.25
10未満 UNDER	+0.2
一般公差 TOLERANCES	

記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE
F	変更 REVISD (J2001-0431)	S.M. T.Y	00/12/8
E	変更及び再作図 REVISD&REDRAWN (J30522)	K.T. H.H	'93/6/1
	APP'D BY '00/12/8	M.FUKUSHIMA	

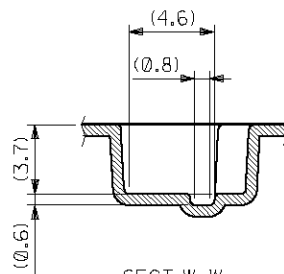
16	16.4	3.7	9.5	53261-0390	3
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	A	ENG. NO.	極致 CKT.
材料 MATERIAL	注記参照 SEE NOTES		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社		
仕上げ FINISH	— / —		REVISE ONLY ON CAD SYSTEM		
適用電線範囲 WIRE RANGE	— / —		TITLE 名称 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT. EMBOSSED TAPE PACKAGE		
被覆外径 INS. RANGE	— / —		DWG. NO. SHEET 1 OF 3 REV		
DRAWN BY '93/6/1 K.TOJO	CHK'D BY '00/12/8 T.YAMAGUCHI	尺度 SCALE	SD-53261-***90		
APP'D BY '00/12/8 M.FUKUSHIMA	尺度 SCALE	F			



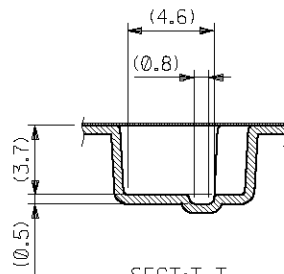
32mm幅キャリアテープ  
32mm WIDTH CARRIER TAPE



24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE



SECT:W-W



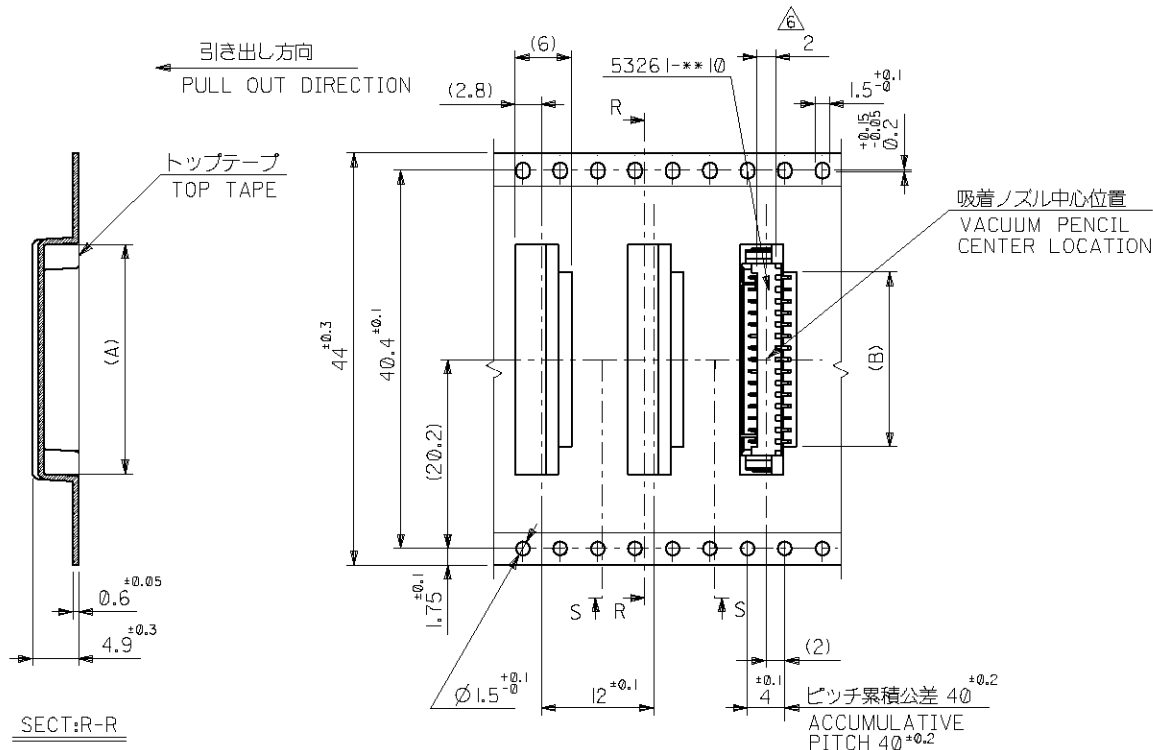
SECT:T-T

32	32.4	16.2	22	53261-1390	13
		14.95	20.75	-1290	12
24	24.4	13.7	19.5	-1190	11
		12.45	18.25	-1090	10
		11.2	17	-0990	9
		9.95	15.75	-0890	8
		8.7	14.5	-0790	7
		7.45	13.25	-0690	6
		6.2	12	-0590	5
		4.95	10.75	53261-0490	4
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	A	ENG. NO.	極致 CKT.

角度 ANGLE	±30				
30以上 OVER	+0.3				
10以上 30未満 OVER UNDER	+0.25	F	変更 REVISED (1022001-00051)	S.M. T.Y	00/12/8
10未満 UNDER	+0.2	E	変更及び再作図 REVISED & REDRAWN (130522)	K.T. H.H	93/6/1
一般公差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD	DR. CHK	日付 DATE

材料 MATERIAL	注記参照 SEE NOTES
仕上げ FINISH	—
適用電線範囲 WIRE RANGE	—
被覆外径 INS. RANGE	—
DRAWN BY '93/6/1	CHK'D BY '00/12/8
K.TOJO	T.YAMAGUCHI
APP'D BY '00/12/8	尺度 SCALE
M.FUKUSHIMA	—

<b>molex</b> MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
<b>REVISE ONLY ON CAD SYSTEM</b>
TITLE 名称 I.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT. EMBOSSD TAPE PACKAGE
DWG. NO. SHEET 2 OF 3 REV SD-53261-**-90



角度 ANGLE	±30																				
30以上 OVER	±0.3																				
10以上 30未満 OVER UNDER	±0.25	F	変更 REVISED	(JC2001-0431)	S.M.	T.Y.	00/12/28														
10未満 UNDER	±0.2	E	変更及び再作図 REVISED & REDRAWN	(J30522)	K.T.	H.H.	93/6/1														
一般公差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD		DR.	CHK.	日付 DATE														
										材料 MATERIAL		注記参照 SEE NOTES		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社							
										仕上げ FINISH		— / —		REVISE ONLY ON CAD SYSTEM							
										適用電線範囲 WIRE RANGE		— / —		TITLE 名称 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT. EMBOSSD TAPE PACKAGE							
										被覆外径 INS. RANGE		— / —		DWG. NO. SHEET 3 OF 3 REV SD-53261-***90							
										DRAWN BY '93/6/1 K.TOJO		CHK'D BY '00/12/28 T.YAMAGUCHI		SCALE — / —							
										APP'D BY '00/12/28 M.FUKUSHIMA				F							